FAIRCHILD SEMICONDUCTOR™

February 1990
Revised August 2000

100331
Low Power Triple D-Type Flip-Flop

General Description

The 100331 contains three D-type, edge-triggered master/slave flip-flops with true and complement outputs, a Common Clock (CP_C), and Master Set (MS) and Master Reset (MR) inputs. Each flip-flop has individual Clock (CP_n), Direct Set (SD_n) and Direct Clear (CD_n) inputs. Data enters a master when both CP_n and CP_C are LOW and transfers to a slave when CP_n or CP_C (or both) go HIGH. The Master Set, Master Reset and individual CD_n and SD_n inputs override the Clock inputs. All inputs have 50 kΩ pull-down resistors.

Features

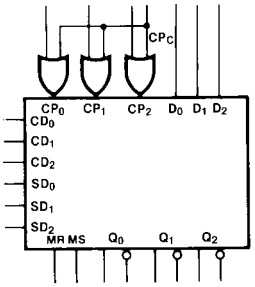
- 35% power reduction of the 100131
- 2000V ESD protection
- Pin/function compatible with 100131
- Voltage compensated operating range = –4.2V to –5.7V
- Available to industrial grade temperature range

Ordering Code:

Order Number	Package Number	Package Description
100331SC	M24B	24-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
100331PC	N24E	24-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-010, 0.400 Wide
100331QC	V28A	28-Lead Plastic Lead Chip Carrier (PLCC), JEDEC MO-047, 0.450 Square
100331QI	V28A	28-Lead Plastic Lead Chip Carrier (PLCC), JEDEC MO-047, 0.450 Square Industrial Temperature Range (–40°C to +85°C)

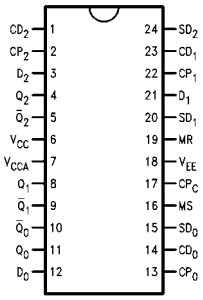
Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol

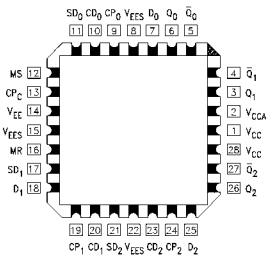


Connection Diagrams

24-Pin DIP/SOIC



28-Pin PLCC



Pin Descriptions

Pin Names	Description
CP_0–CP_2	Individual Clock Inputs
CP_C	Common Clock Input
D_0–D_2	Data Inputs
CD_0–CD_2	Individual Direct Clear Inputs
SD_n	Individual Direct Set Inputs
MR	Master Reset Input
MS	Master Set Input
Q_0-Q_2	Data Outputs
$\overline{Q}_0$–$\overline{Q}_2$	Complementary Data Outputs

Truth Tables

Synchronous Operation (Each Flip-Flop)

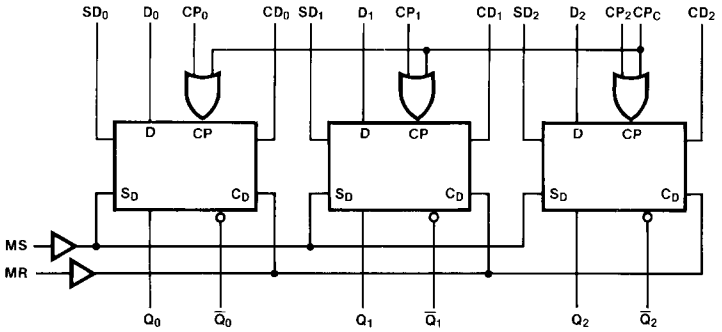
Inputs					Outputs
D_n	CP_n	CP_C	MS SD_n	MR CD_n	$Q_n(t+1)$
L	↗	L	L	L	L
H	↗	L	L	L	H
L	L	↗	L	L	L
H	L	↗	L	L	H
X	L	L	L	L	$Q_n(t)$
X	H	X	L	L	$Q_n(t)$
X	X	H	L	L	$Q_n(t)$

Asynchronous Operation (Each Flip-Flop)

Inputs					Outputs
D_n	CP_n	CP_C	MS SD_n	MR CD_n	$Q_n(t+1)$
X	X	X	H	L	H
X	X	X	L	H	L
X	X	X	H	H	U

H = HIGH Voltage Level
L = LOW Voltage Level
X = Don't Care
U = Undefined
t = Time before CP Positive Transition
t + 1 = Time after CP Positive Transition
↗ = LOW-to-HIGH Transition

Logic Diagram



Absolute Maximum Ratings (Note 1)

Storage Temperature (T_{STG})	−65°C to +150°C
Maximum Junction Temperature (T_J)	+150°C
Pin Potential to Ground Pin (V_{EE})	−7.0V to +0.5V
Input Voltage (DC)	V_{EE} to +0.5V
Output Current	
(DC Output HIGH)	−50 mA
ESD (Note 2)	≤ 2000V

Recommended Operating Conditions

Case Temperature (T_C)	
Commercial	0°C to +85°C
Industrial	−40°C to +85°C
Supply Voltage (V_{EE})	−5.7V to −4.2V

Note 1: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum rating. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 2: ESD testing conforms to MIL-STD-883, Method 3015.

Commercial Version

DC Electrical Characteristics (Note 3)

V_{EE} = −4.2V to −5.7V, V_{CC} = V_{CCA} = GND, T_C = 0°C to +85°C

Symbol	Parameter	Min	Typ	Max	Units	Conditions	
V_{OH}	Output HIGH Voltage	−1025	−955	−870	mV	V_{IN} = V_{IH} (Max)	Loading with
V_{OL}	Output LOW Voltage	−1830	−1705	−1620	mV	or V_{IL} (Min)	50Ω to −2.0V
V_{OHC}	Output HIGH Voltage	−1035			mV	V_{IN} = V_{IH} (Min)	Loading with
V_{OLC}	Output LOW Voltage			−1610	mV	or V_{IL} (Max)	50Ω to −2.0V
V_{IH}	Input HIGH Voltage	−1165		−870	mV	Guaranteed HIGH Signal for All Inputs	
V_{IL}	Input LOW Voltage	−1830		−1475	mV	Guaranteed LOW Signal for All Inputs	
I_{IL}	Input LOW Current	0.5			µA	V_{IN} = V_{IL} (Min)	
I_{IH}	Input HIGH Current			240	µA	V_{IN} = V_{IH} (Max)	
I_{EE}	Power Supply Current	−122		−65	mA	Inputs OPEN	

Note 3: The specified limits represent the "worst case" value for the parameter. Since these values normally occur at the temperature extremes, additional noise immunity and guardbanding can be achieved by decreasing the allowable system operating ranges. Conditions for testing shown in the tables are chosen to guarantee operation under "worst case" conditions.

Commercial Version (Continued)
DIP AC Electrical Characteristics

V_{EE} = –4.2V to –5.7V, V_{CC} = V_{CCA} = GND

Symbol	Parameter	T_C = 0°C		T_C = +25°C		T_C = +85°C		Units	Conditions	
		Min	Max	Min	Max	Min	Max			
f_{MAX}	Toggle Frequency	375		375		375		MHz	Figures 2, 3	
t_{PLH} t_{PHL}	Propagation Delay CP_C to Output	0.75	2.00	0.75	2.00	0.75	2.00	ns	Figures 1, 3	
t_{PLH} t_{PHL}	Propagation Delay CP_n to Output	0.75	2.00	0.75	2.00	0.75	2.00	ns	Figures 1, 3	
t_{PLH} t_{PHL}	Propagation Delay CD_n, SD_n to Output	0.70	1.70	0.70	1.70	0.70	1.80	ns	CP_n, CP_C = L	Figures 1, 4
t_{PLH} t_{PHL}		0.70	2.00	0.70	2.00	0.70	2.00		CP_n, CP_C = H	
t_{PLH} t_{PHL}	Propagation Delay MS, MR to Output	1.10	2.60	1.10	2.60	1.10	2.60	ns	CP_n, CP_C = L	
t_{PLH} t_{PHL}		1.10	2.80	1.10	2.80	1.10	2.80		CP_n, CP_C = H	
t_{TLH} t_{THL}	Transition Time 20% to 80%, 80% to 20%	0.35	1.30	0.35	1.30	0.35	1.30	ns	Figures 1, 3, 4	
t_S	Setup Time D_n	0.40		0.40		0.40		ns	Figure 5	
	CD_n, SD_n (Release Time)	1.30		1.30		1.30			Figure 4	
	MS, MR (Release Time)	2.30		2.30		2.30				
t_H	Hold Time D_n	0.5		0.5		0.7		ns	Figure 5	
t_{PW}(H)	Pulse Width HIGH CP_n, CP_C, CD_n, SD_n, MR, MS	2.00		2.00		2.00		ns	Figures 3, 4	

SOIC and PLCC AC Electrical Characteristics

V_{EE} = –4.2V to –5.7V, V_{CC} = V_{CCA} = GND

Symbol	Parameter	T_C = 0°C		T_C = +25°C		T_C = +85°C		Units	Conditions	
		Min	Max	Min	Max	Min	Max			
f_{MAX}	Toggle Frequency	400		400		400		MHz	Figures 2, 3	
t_{PLH} t_{PHL}	Propagation Delay CP_C to Output	0.75	1.80	0.75	1.80	0.75	1.80	ns	Figures 1, 3	
t_{PLH} t_{PHL}	Propagation Delay CP_n to Output	0.75	1.80	0.75	1.80	0.75	1.80	ns	Figures 1, 3	
t_{PLH} t_{PHL}	Propagation Delay CD_n, SD_n to Output	0.70	1.50	0.70	1.50	0.70	1.60	ns	CP_n, CP_C =L	Figures 1, 4
t_{PLH} t_{PHL}		0.80	1.80	0.70	1.80	0.70	1.80		CP_n, CP_C = H	
t_{PLH} t_{PHL}	Propagation Delay MS, MR to Output	1.10	2.40	1.10	2.40	1.10	2.40	ns	CP_n, CP_C = L	
t_{PLH} t_{PHL}		1.10	2.60	1.10	2.60	1.10	2.60		CP_n, CP_C = H	
t_{TLH} t_{THL}	Transition Time 20% to 80%, 80% to 20%	0.35	1.10	0.35	1.10	0.35	1.10	ns	Figures 1, 3, 4	
t_S	Setup Time D_n	0.30		0.30		0.30		ns	Figure 5	
	CD_n, SD_n (Release Time)	1.20		1.20		1.20			Figure 4	
	MS, MR (Release Time)	2.20		2.20		2.20				
t_H	Hold Time D_n	0.5		0.5		0.7		ns	Figure 5	
t_{PW}(H)	Pulse Width HIGH CP_n, CP_C, CD_n, SD_n, MR, MS	2.00		2.00		2.00		ns	Figures 3, 4	

Commercial Version (Continued)

Symbol	Parameter	T_C = 0°C		T_C = +25°C		T_C = +85°C		Units	Conditions	
		Min	Max	Min	Max	Min	Max			
t_{PLH} t_{PHL}	Propagation Delay CP_C to Output	0.75	1.40	0.75	1.40	0.80	1.50	ns	Figures 1, 3 PLCC Only	
t_{PLH} t_{PHL}	Propagation Delay CP_n to Output	0.70	1.40	0.75	1.40	0.80	1.50	ns		
t_{PLH} t_{PHL}	Propagation Delay CD_n, SD_n to Output	0.70	1.50	0.70	1.50	0.80	1.60	ns	CP_n, CP_C =L PLCC Only	Figures 1, 4
t_{PLH} t_{PHL}		0.80	1.70	0.80	1.70	0.80	1.80		CP_n, CP_C = H PLCC Only	
t_{PLH} t_{PHL}	Propagation Delay MS, MR to Output	1.10	2.00	1.10	2.00	1.20	2.10	ns	CP_n, CP_C = L PLCC Only	
t_{PLH} t_{PHL}		1.20	2.10	1.20	2.10	1.30	2.20		CP_n, CP_C = H PLCC Only	
t_{OSHL}	Maximum Skew Common Edge Output-to-Output Variation Common Clock to Output Path		100		100		100	ps	PLCC Only (Note 4)	
t_{OSHL}	Maximum Skew Common Edge Output-to-Output Variation CP_n to Output Path		235		235		235	ps	PLCC Only (Note 4)	
t_{OSLH}	Maximum Skew Common Edge Output-to-Output Variation Common Clock to Output Path		120		120		120	ps	PLCC Only (Note 4)	
t_{OSLH}	Maximum Skew Common Edge Output-to-Output Variation CP_n to Output Path		275		275		275	ps	PLCC Only (Note 4)	
t_{OST}	Maximum Skew Opposite Edge Output-to-Output Variation Common Clock to Output Path		125		125		125	ps	PLCC Only (Note 4)	
t_{OST}	Maximum Skew Opposite Edge Output-to-Output Variation CP_n to Output Path		265		265		265	ps	PLCC Only (Note 4)	
t_{PS}	Maximum Skew Pin (Signal) Transition Variation Common Clock to Output Path		90		90		90	ps	PLCC Only (Note 4)	
t_{PS}	Maximum Skew Pin (Signal) Transition Variation CP_n to Output Path		90		90		90	ps	PLCC Only (Note 4)	

Note 4: Output-to-Output Skew is defined as the absolute value of the difference between the actual propagation delay for any outputs within the same packaged device. The specifications apply to any outputs switching in the same direction either HIGH-to-LOW (t_{OSHL}), or LOW-to-HIGH (t_{OSLH}), or in opposite directions both HL and LH (t_{OST}). Parameters t_{OST} and t_{PS} guaranteed by design.

Industrial Version

PLCC DC Electrical Characteristics (Note 5)

V_{EE} = −4.2V to −5.7V, V_{CC} = V_{CCA} = GND, T_C = −40°C to +85°C

Symbol	Parameter	T_C = −40°C		T_C = 0°C to +85°C		Units	Conditions	
		Min	Max	Min	Max			
V_{OH}	Output HIGH Voltage	−1085	−870	−1025	−870	mV	V_{IN} = V_{IH} (Max)	Loading with
V_{OL}	Output LOW Voltage	−1830	−1575	−1830	−1620	mV	or V_{IL} (Min)	50Ω to −2.0V
V_{OHC}	Output HIGH Voltage	−1095		−1035		mV	V_{IN} = V_{IH} (Min)	Loading with
V_{OLC}	Output LOW Voltage		−1565		−1610	mV	or V_{IL} (Max)	50Ω to −2.0V
V_{IH}	Input HIGH Voltage	−1170	−870	−1165	−870	mV	Guaranteed HIGH Signal for All Inputs	
V_{IL}	Input LOW Voltage	−1830	−1480	−1830	1475	mV	Guaranteed LOW Signal for All Inputs	
I_{IL}	Input LOW Current	0.5		0.5		µA	V_{IN} = V_{IL} (Min)	
I_{IH}	Input HIGH Current		300		240	µA	V_{IN} = V_{IH} (Max)	
I_{EE}	Power Supply Current	−122	−60	−122	−65	mA	Inputs Open	

Note 5: The specified limits represent the "worst case" value for the parameter. Since these values normally occur at the temperature extremes, additional noise immunity and guardbanding can be achieved by decreasing the allowable system operating ranges. Conditions for testing shown in the tables are chosen to guarantee operation under "worst case" conditions.

PLCC AC Electrical Characteristics

V_{EE} = −4.2V to −5.7V, V_{CC} = V_{CCA} = GND

Symbol	Parameter	T_C = −40°C		T_C = +25°C		T_C = +85°C		Units	Conditions	
		Min	Max	Min	Max	Min	Max			
f_{MAX}	Toggle Frequency	375		400		400		MHz	Figures 2, 3	
t_{PLH} t_{PHL}	Propagation Delay CP_C to Output	0.75	1.80	0.75	1.80	0.75	1.80	ns	Figures 1, 3	
t_{PLH} t_{PHL}	Propagation Delay CP_n to Output	0.70	1.80	0.75	1.80	0.75	1.80	ns		
t_{PLH} t_{PHL}	Propagation Delay CD_n, SD_n to Output	0.60	1.50	0.70	1.50	0.70	1.60	ns	CP_n, CP_C = L	Figures 1, 4
t_{PLH} t_{PHL}		0.70	1.80	0.70	1.80	0.70	1.80		CP_n, CP_C = H	
t_{PLH} t_{PHL}	Propagation Delay MS, MR to Output	1.10	2.40	1.10	2.40	1.10	2.40	ns	CP_n, CP_C = L	
t_{PLH} t_{PHL}		1.10	2.60	1.10	2.60	1.10	2.60		CP_n, CP_C = H	
t_{TLH} t_{THL}	Transition Time 20% to 80%, 80% to 20%	0.20	1.40	0.35	1.10	0.35	1.10	ns	Figures 1, 3, 4	
t_S	Setup Time									
	D_n	1.00		0.30		0.30		ns	Figure 5	
	CD_n, SD_n (Release Time)	1.50		1.20		1.20			Figure 4	
	MS, MR (Release Time)	2.50		2.20		2.20				
t_H	Hold Time D_n	0.7		0.5		0.7		ns	Figure 5	
t_{PW}(H)	Pulse Width HIGH CP_n, CP_C, CD_n, SD_n, MR, MS	2.00		2.00		2.00		ns	Figures 3, 4	

Test Circuits

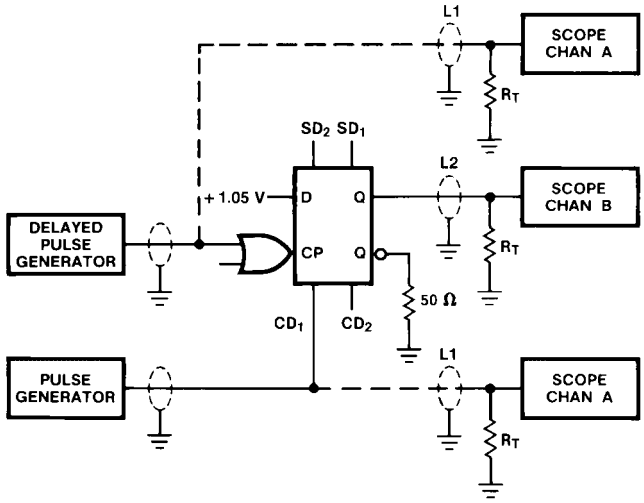
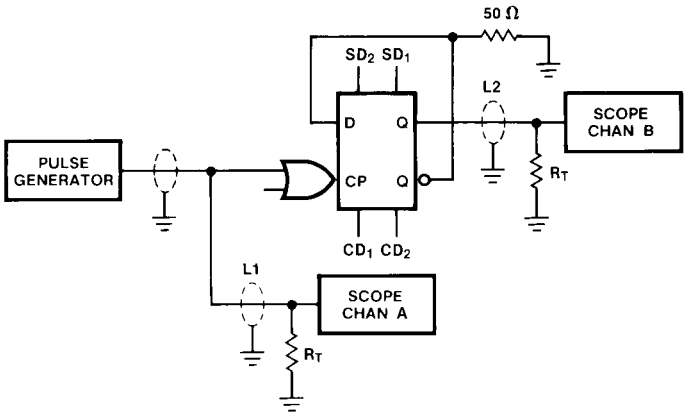


FIGURE 1. AC Test Circuit



Notes:

V_{CC}, V_{CCA} = +2V, V_{EE} = −2.5V

L1 and L2 = Equal length 50Ω impedance lines

R_T = 50Ω terminator internal to scope

Decoupling 0.1 µF from GND to V_{CC} and V_{EE}

All unused outputs are loaded with 50Ω to GND

C_L = Fixture and stray capacitance ≤ 3 pF

FIGURE 2. Toggle Frequency Test Circuit

Switching Waveforms

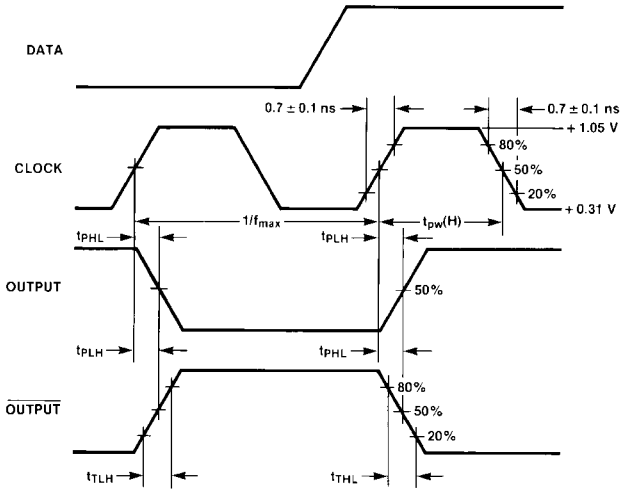


FIGURE 3. Propagation Delay (Clock) and Transition Times

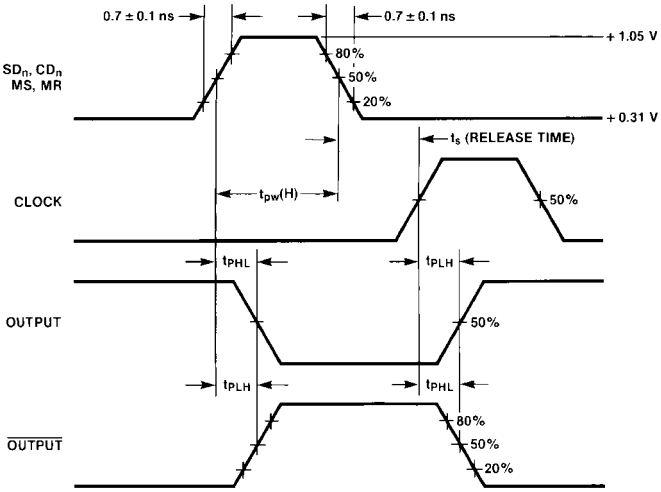


FIGURE 4. Propagation Delay (Resets)

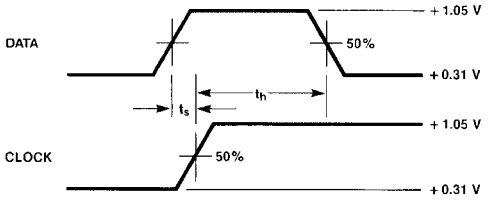


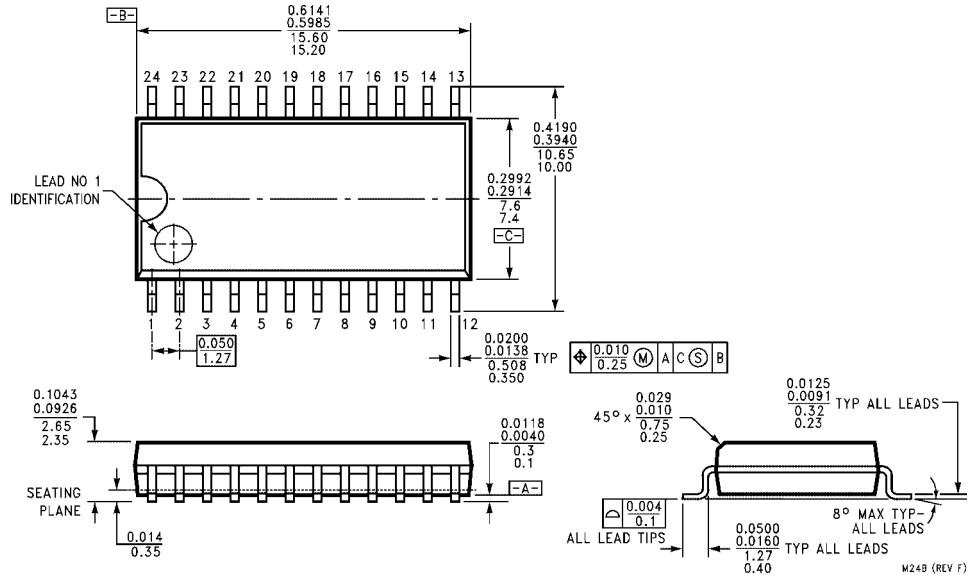
FIGURE 5. Data Setup and Hold Time

Note:

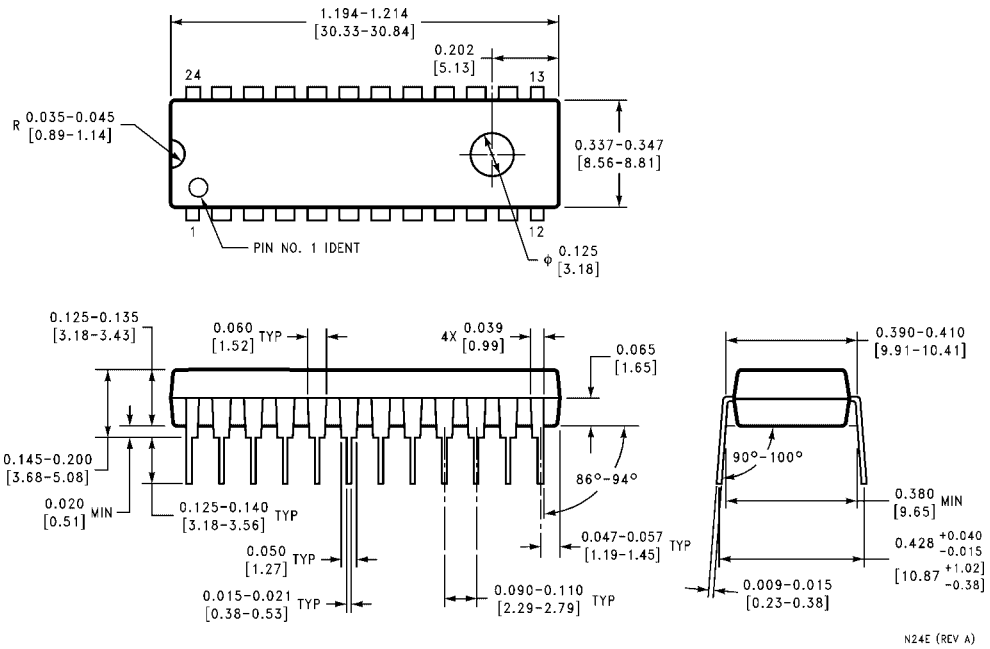
t_S is the minimum time before the transition of the clock that information must be present at the data input.

t_H is the minimum time after the transition of the clock that information must remain unchanged at the data input.

Physical Dimensions inches (millimeters) unless otherwise noted

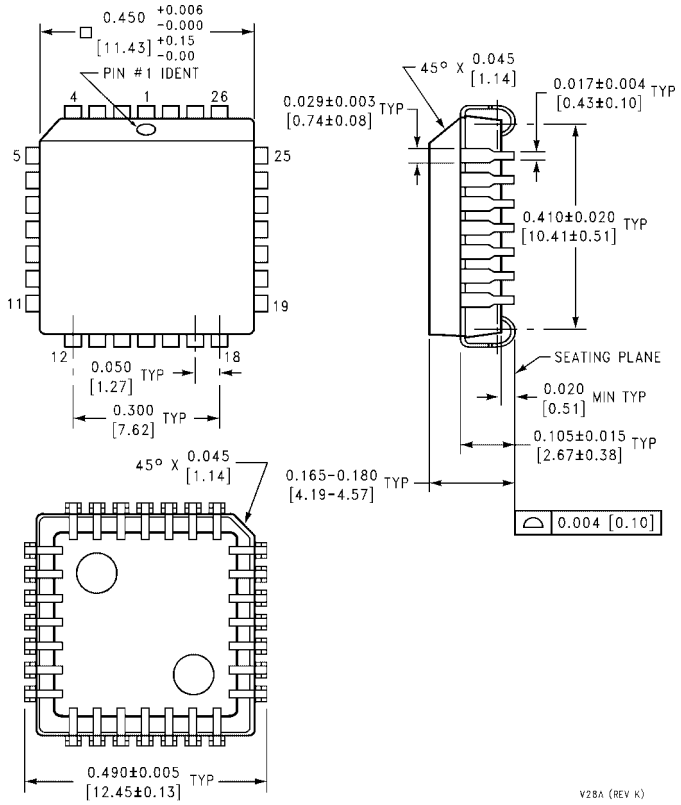


24-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
Package Number M24B



24-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-010, 0.400 Wide
Package Number N24E

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



28-Lead Plastic Lead Chip Carrier (PLCC), JEDEC MO-047, 0.450 Square
Package Number V28A

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